

ABSTRACT

A cutting device 15 that, after a sheet S is stuck on a wafer W on a sticking table 13, cuts the sheet S along the outer edge of the wafer. The cutting device 15 comprises a robot body 62 disposed beside the sticking table 13 and a cutter blade 63 supported by a tool holding chuck 69 positioned at the front end of the robot body 62. The cutter blade 63 is detachably attached to the tool holding chuck 69 so as to be replaceable and is arranged so as to cut the sheet S in a state that the posture thereof is adjusted along a preset movement track.